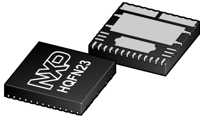

SOT1631-4

HQFN23; plastic, thermally enhanced quad; flat non-leaded package; 23 terminals; 0.9 mm pitch; 12 mm x 12 mm x 2.1 mm body

14 December 2016 Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HQFN23
Package type industry code	HQFN23
Package style descriptive code	HQFN (thermal enhanced quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	21-1-2016
Manufacturer package code	98ASA00428D

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		-	-	12	-	mm
E	package width		-	-	12	-	mm
A	seated height		-	-	2.1	2.2	mm
e	nominal pitch		-	-	0.9	-	mm
n_2	actual quantity of termination		-	-	23	-	

2. Package outline

Fig. 1. Package outline HQFN23 (SOT1631-4)

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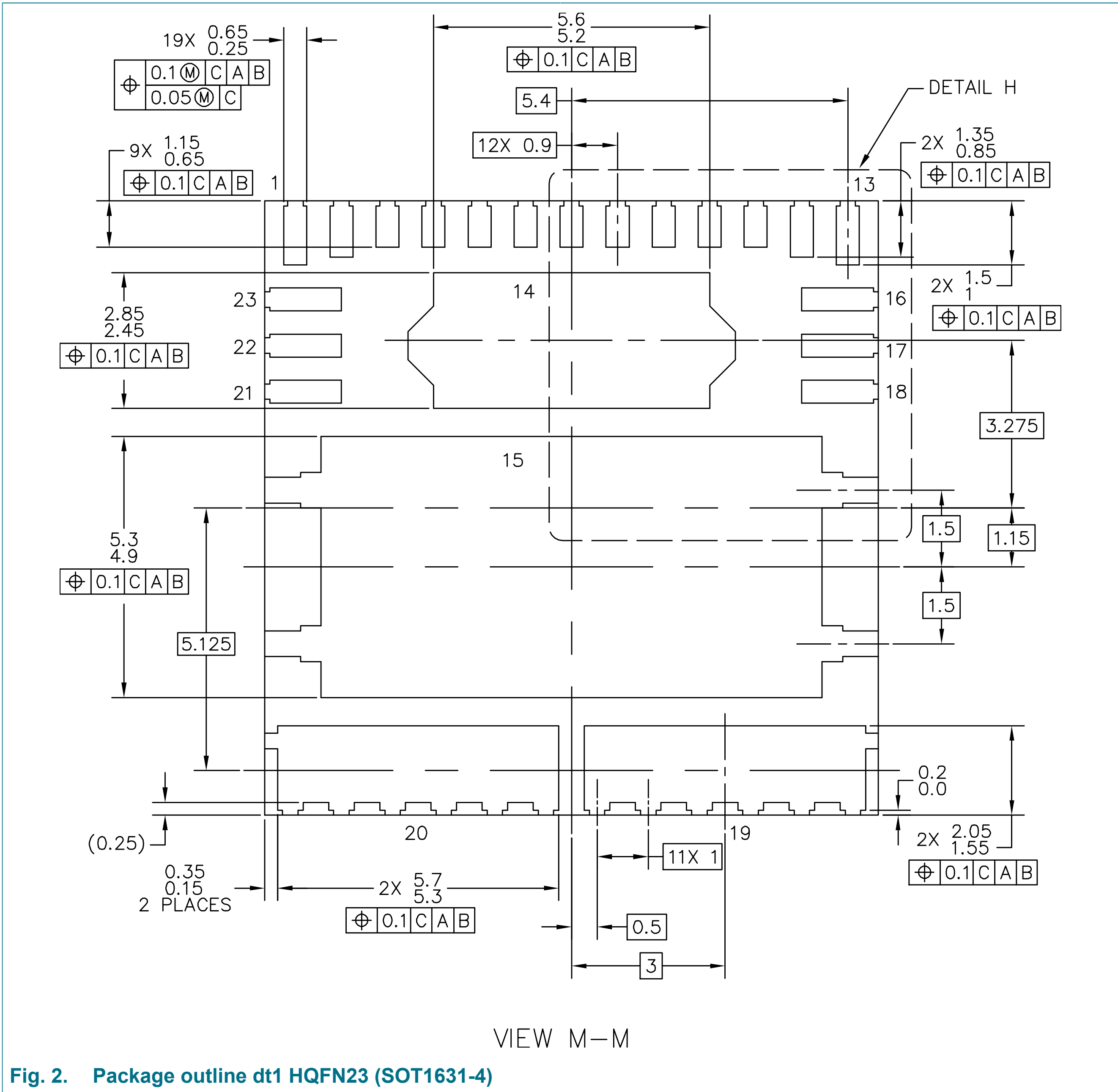

Fig. 2. Package outline dt1 HQFN23 (SOT1631-4)

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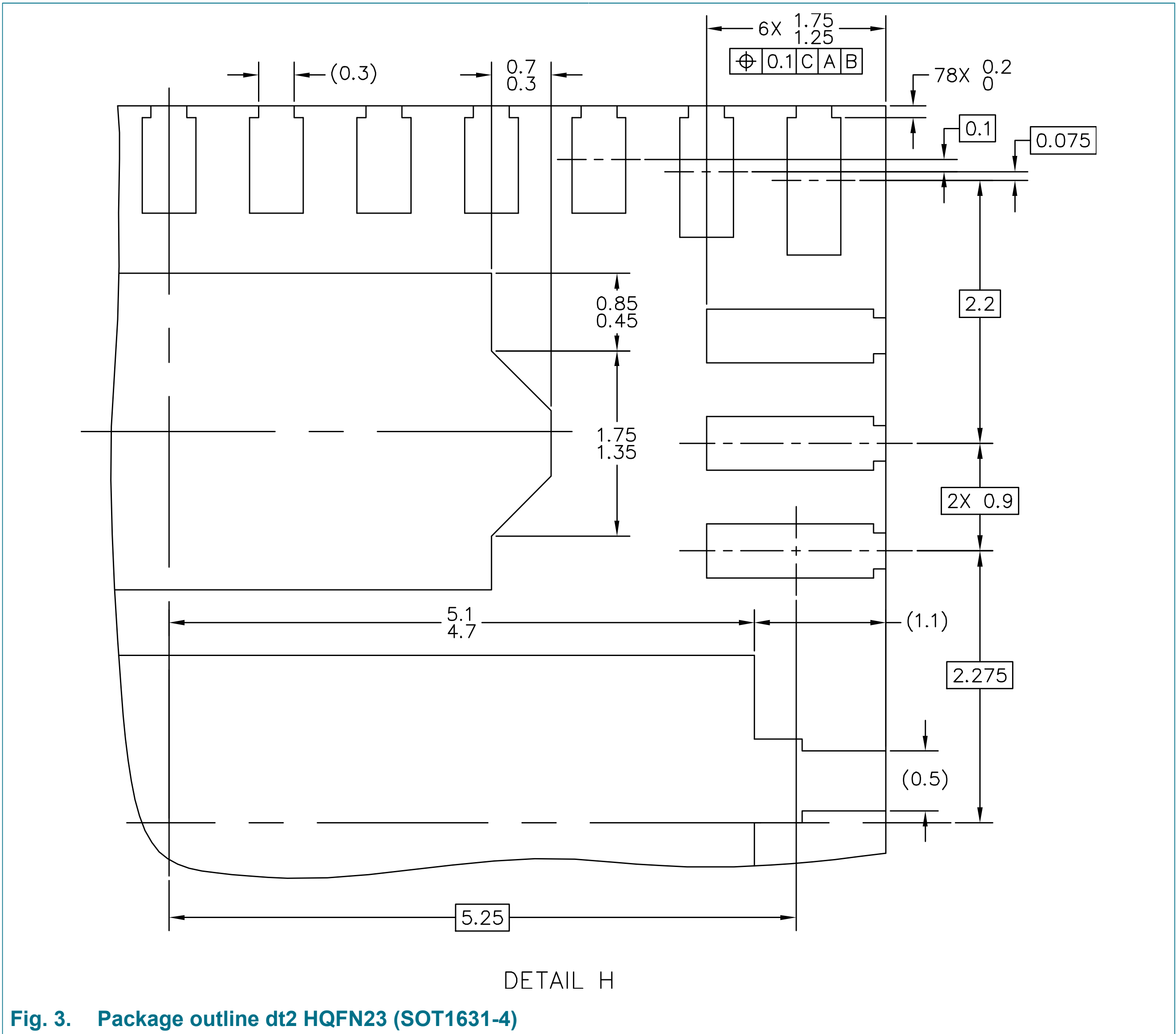

Fig. 3. Package outline dt2 HQFN23 (SOT1631-4)

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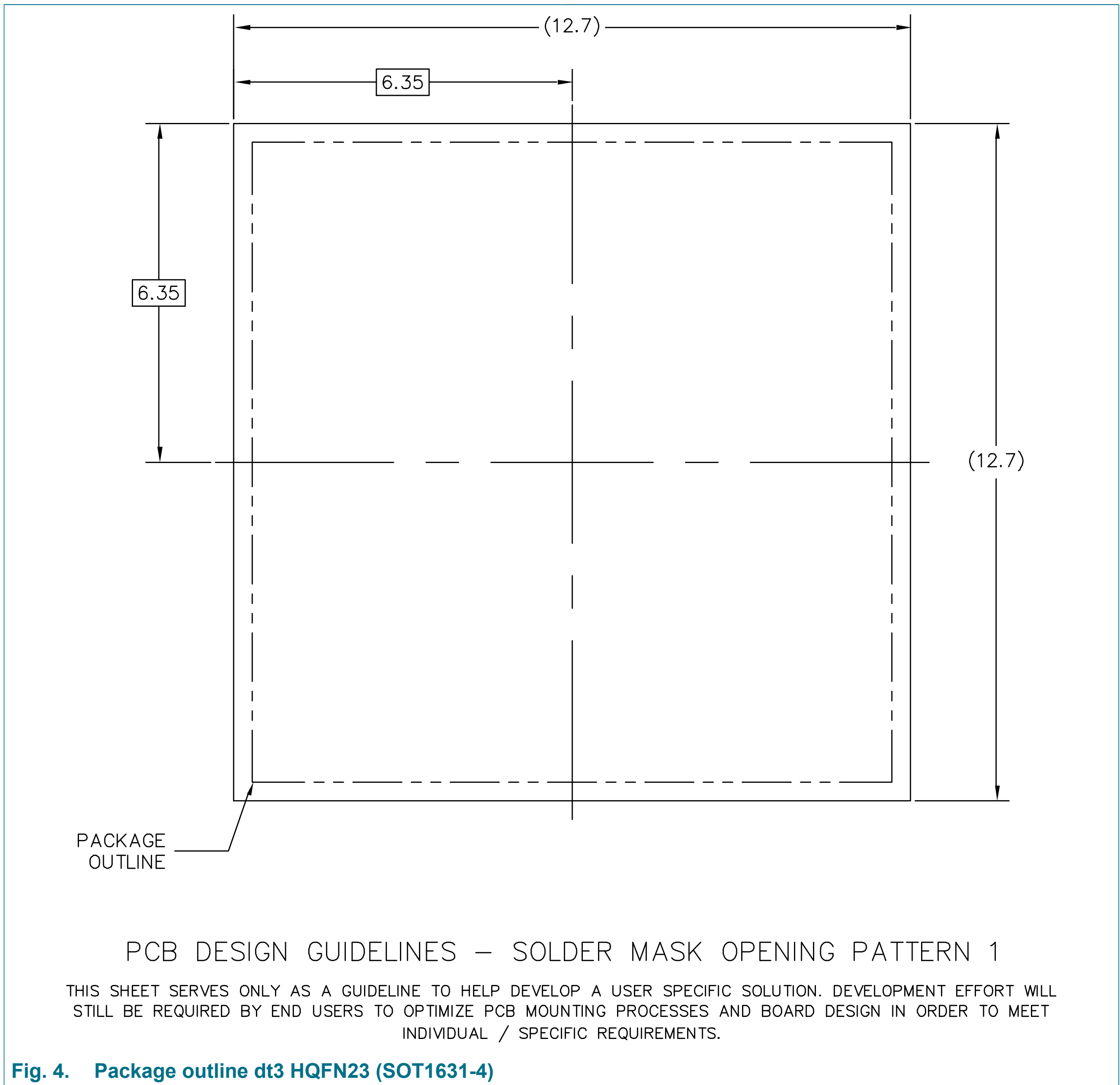

Fig. 4. Package outline dt3 HQFN23 (SOT1631-4)

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HQFN23; plastic, thermally enhanced quad; flat non-leaded package; 23 terminals; 0.9 mm pitch; 12 mm x 12 mm x 2.1 mm body

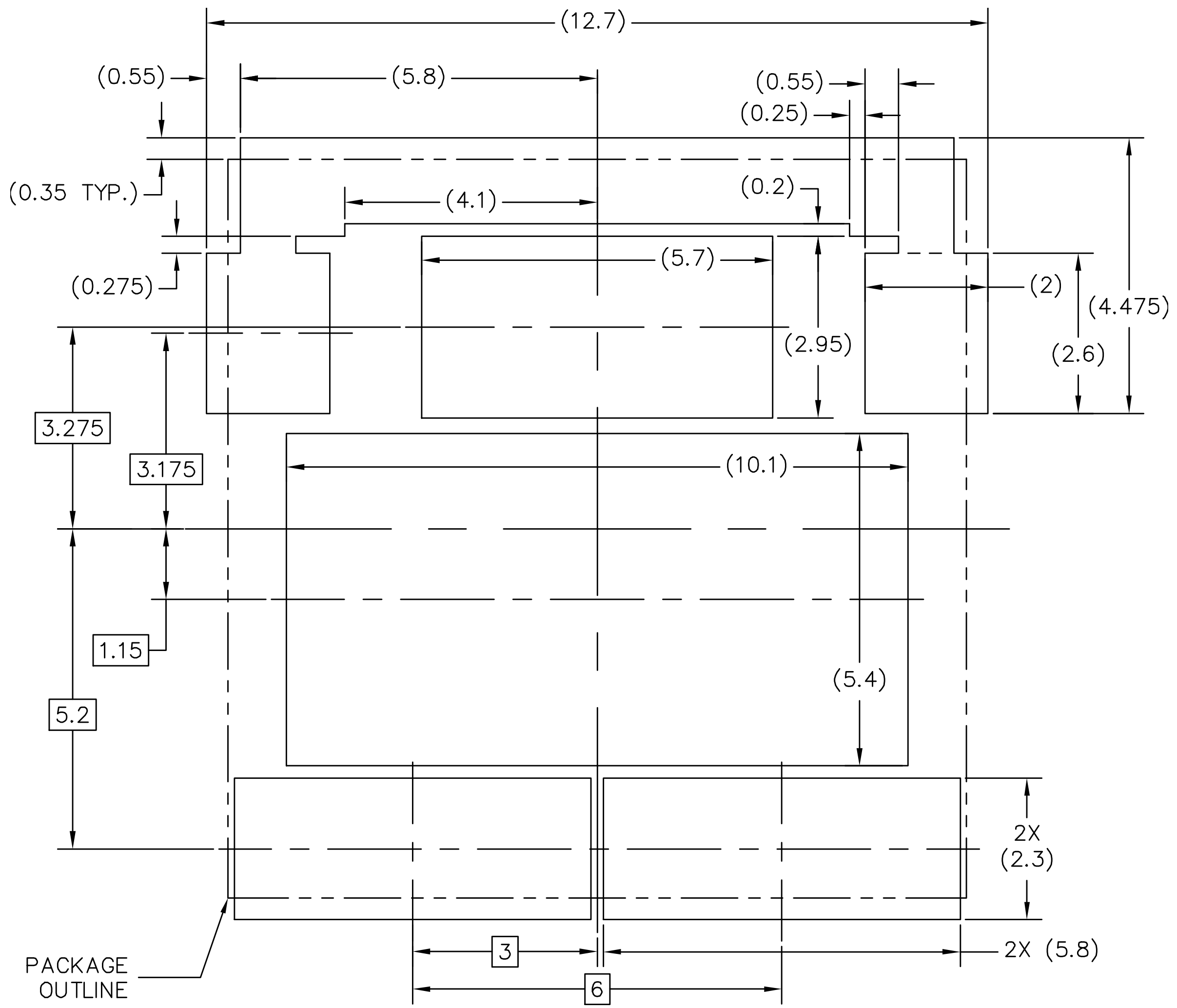

Fig. 5. Package outline dt4 HQFN23 (SOT1631-4)

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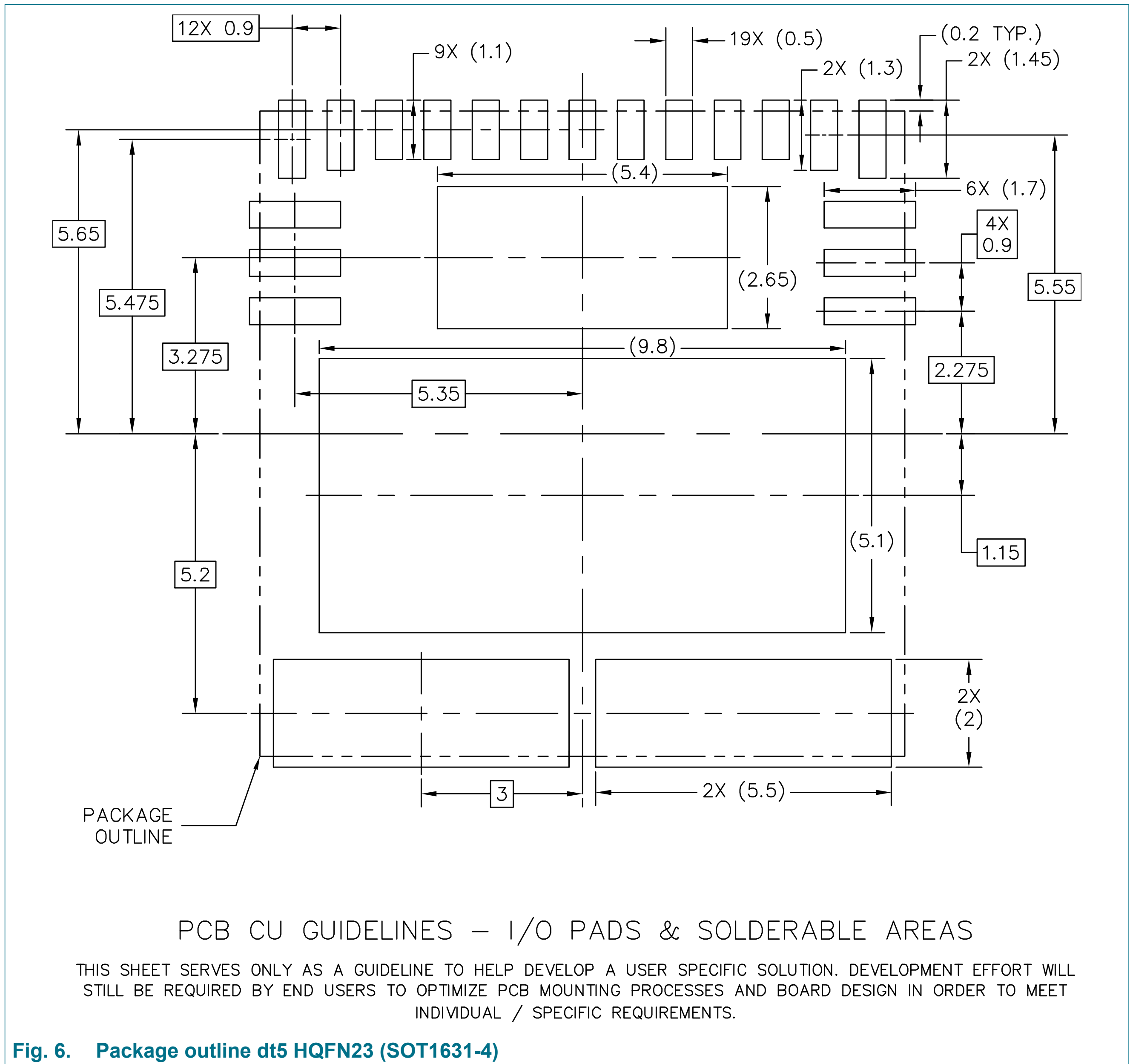

Fig. 6. Package outline dt5 HQFN23 (SOT1631-4)

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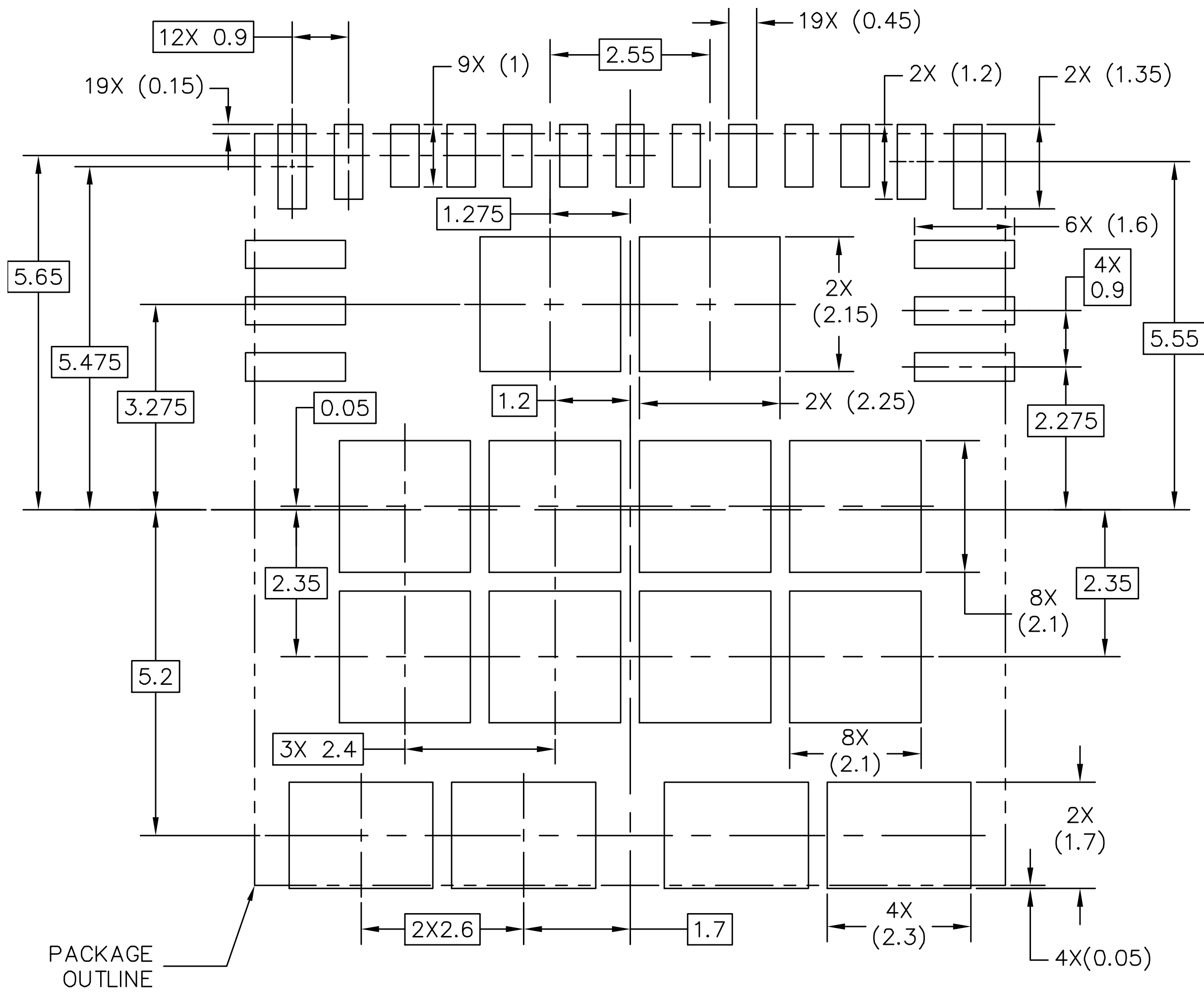

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Fig. 7. Package outline dt6 HQFN23 (SOT1631-4)

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M−1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF−PQFP−N.
4. COPLANARITY APPLIES TO LEADS AND CORNER LEADS.
5. MINIMUM METAL GAP IS GUARANTEED TO BE 0.25 MM.

Fig. 8. Package outline note HQFN23 (SOT1631-4)

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